# Status of DO and TF firmware IAPP-FTK General Assembly / Executive Board meeting

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Status of DO and TF firmware

General description DO details Combiner details TF details Resource utilization

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Testing and integration
Ultrascale board DO-TE designed
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# General Description

- High performance implementation
- 200MHits/layer/sec DO input rate
- up to 2GFits/sec TF performance
- 300ns fixed total DO+TF latency (inside the FPGA device)



#### DO and TF firmware

Testing and integration

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# DO details



- Fast architecture, 400MHz fmax
- Two modes of operation (write, read)
- Write mode stores stubs in the database and sends the coarse representation to the AMChips
- Read mode gets the results from the AMChips, decodes it using external RAM, and gets the stubs from the database to send to the combiners
- Read mode especially optimized for quick stub retrieval, due to use of very wide memories and parallelism
- Two DO units can fit for ping-pong operation (one writes, other reads)
- TC builder (see next talk) can be integrated on each output to reduce tracks

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#### Combiner details

- Calculates all valid track combinations of a pattern
- Long critical path leads to low op. frequency wrt TF
- We use two combiner modules for each TF module
- Each detected pattern gets assigned to a combiner, a couple of patterns with many combinations may take a long time (while the rest are done)
- Future optimization: modify it to count up/down so two combiners can share one road



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# TF details



- Extensive use of DSP units
- Frequency of 500MHz+
- One fit/clock cycle
- $\bullet$  < 100ns latency
- Multiple units can run in parallel
- 4 units can fit in a mid-grade device giving 2GFits/sec
- Fit coefficients stored in BRAM memory resources
- If we can do with a small number of coefficient sets, possible to fit more TF units in high grade devices

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#### Resource utilization

Туре	CLB LUTs	CLB Regs	BRAMs	DSPs
(total)	(240k)	(480k)	(600)	(1920)
DO	56k	93k	164	0
Comb	0.67k	1.5k	4	0
TF	0.2k	40k	36	190

Table: Resource utilization of each component (totals for XCKU040)

Ultrascale board DO-TF tests Mezzanine tests and integration

#### DO and TF firmware

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- Ultrascale board DO-TF tests
- Mezzanine tests and integration

### Ultrascale board DO-TF tests

- To test the DO and TF an Ultrascale development board was used
- Verification was done utilizing an IPBus connection over Ethernet
- SystemVerilog testbench running on Modelsim generates random events, emulates the AMChip functionality, and verifies the results
- Tested for 1200 randomly generated events, with 5-15k track candidates each, no major bugs
- A minor bug has to be fixed, but it just affects < 0.001% of track candidates so we can proceed



Ultrascale board DO-TF tests Mezzanine tests and integration

#### Mezzanine tests and integration



- Integration has to proceed towards a more realistic system
- The Ultrascale board will play the role of the Pulsar, sending stubs and receiving the track parameters to forward to the testbench for validation
- The mezzanine currently hosts 4 AMChips and the Kintex-7 FPGA where the firmware will be integrated
- The whole processing chain will initially be verified for single muon events
- This work is currently in progress

# Thank you!

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